

ON Semiconductor				10/15/2019	
Base Part		FDN8601	HF	Pb-free	
Orderable Part		FDN8601	Total weight (mg)	10.813	
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight	
Die	0.283	Silicon (Si)	7440-21-3	100	
Die Attach	0.054	Silver (Ag)	7440-22-4	79.5	
		Phenolic Resin-2	54208-63-8	20.5	
Lead Frame	3.684	Zinc (Zn)	7440-66-6	0.13572204	
		Iron (Fe)	7439-89-6	2.38870793	
		Copper (Cu)	7440-50-8	97.44842562	
		Phosphorus (P)	7723-14-0	0.02714441	
Mold Compound-Black	6.41	Ortho Cresol Novolac Resin	29690-82-2	29.00156006	
		Carbon Black (C)	1333-86-4	0.99843994	
		Fused Silica (SiO2)	60676-86-0	70	
Plating	0.306	Tin (Sn)	7440-31-5	100	
Wire Bond - Au	0.076	Gold (Au)	7440-57-5	100	
<p>Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:</p> <p>http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF</p>					